

US/200100
11/11/97
250
Class
Subclass
ISSUE CLASSIFICATION
SCANNED

UTILITY SERIAL NUMBER
PATENT DATE SEP 14 1999
PATENT NUMBER
5952646

SERIAL NUMBER
FILING DATE
CLASS
SUBCLASS
GROUP ART UNIT
EXAMINER

APPLICANTS
None

yes United Kingdom 96269725 Dec. 27, 1996

Foreign priority claimed
35 USC 119 conditions met
Verified and Acknowledged
AS FILED
STATE OR COUNTRY
SHEETS DRWGS.
TOTAL CLAIMS
INDEP. CLAIMS
FILING FEE RECEIVED
ATTORNEY'S DOCKET NO.

ADDRESS
Low Temperature Bump-Bonding Semiconductor Imaging Device
TITLE
U.S. DEPT. OF COMM./PAT. & TM--PTO-436L (Rev.12-94)

PARTS OF APPLICATION
FILED SEPARATELY
NOTICE OF ALLOWANCE MAILED
4-9-99
Assistant Examiner
ISSUE FEE
Amount Due
Date Paid
Label Area
PREPARED FOR ISSUE
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form PTO-436A
SCAN 8 CB
Formal Drawings
QC
DWG
(FACE)

ISSUE FEE IN FILE